



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-31
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS Material Declaration Champions
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	B5NX*U39DBA1	A	Z6GA	2015-07-31
Amount	UoM	Unit type	ST ECOPACK Grade	
217.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x1.9	28	No lead	
Comment	Package: QFPN 7x7x1.9 28 PITCH 0.8; MD valid for AIS326DQ - AIS326DQTR			

QueryList : ROHS directive 2011/65/EU _ July 2011

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption id.	Description	
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound	

QueryList : REACH-15th June 2015

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSNX*U39DBA1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	23.307	mg	supplier	die	Silicon (Si)	7440-21-3		22.361	mg	959411	103046
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	472	51
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	257	28
				supplier	Passivation	Silicon Oxide	7631-86-9		0.080	mg	3432	369
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-l-Electrical and e	0.769	mg	32994	3544
Leadframe	Copper & its alloys	37.320	mg	supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.080	mg	3432	369
				supplier	alloy	Copper (Cu)	7440-50-8		35.939	mg	962996	165618
				supplier	alloy	Iron (Fe)	7439-89-6		0.845	mg	22642	3894
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.051	mg	1367	235
				supplier	alloy	Zinc (Zn)	7440-66-6		0.044	mg	1179	203
Die attach	Other inorganic materials	0.927	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.441	mg	11817	2032
				supplier	glue or tape (choose)	Epoxy resin	Proprietary		0.371	mg	400216	1710
				supplier	glue or tape	Tetrafluoroethylene	9002-84-0		0.408	mg	440129	1880
				supplier	glue or tape	Polybutadiene polymer	25655-35-0		0.111	mg	119741	512
				supplier	glue or tape	Silane	7803-62-5		0.028	mg	30205	129
Die attach 2	Other inorganic materials	0.399	mg	supplier	glue or tape	maleic anhydride	108-31-6		0.009	mg	9709	41
				supplier	glue or tape	silicone resin	Proprietary		0.367	mg	919799	1691
				supplier	glue or tape	Polydimethyl hydrogenmethyl siloxane	68037-59-2		0.016	mg	40100	74
				supplier	glue or tape	[3-(2,3-epoxypropoxy)propyl] trimethoxysilane	2530-83-8		0.016	mg	40100	74
				supplier	wire	Gold (Au)	7440-57-5		0.388	mg	1000000	1788
Encapsulation	Other Organic Materials	154.641	mg	supplier	mold compound	Silica, vitreous	60676-86-0		143.197	mg	925996	659894
				supplier	mold compound	epoxy resin	85954-11-6		6.186	mg	40002	28507
				supplier	mold compound	phenol resin	26834-02-6		4.639	mg	29999	21378
				supplier	mold compound	carbon black	1333-86-4		0.619	mg	4003	2853
connections coating	Solder	0.018	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.018	mg	1000000	83